

U.S. Patent Application Serial No.: 10/647,263
Docket No.: 514372000110
Confirmation No.: 2075 Group Art Unit: 2826
Title: THERMALLY CONDUCTIVE SUBSTRATE, THERMALLY
CONDUCTIVE SUBSTRATE MANUFACTURING METHOD AND
POWER MODULE
Inventors: Yoshihisa YAMASHITA, et al.
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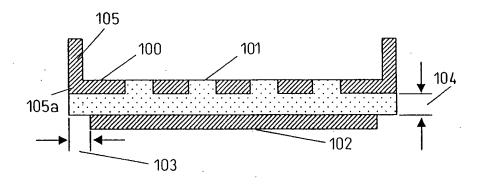
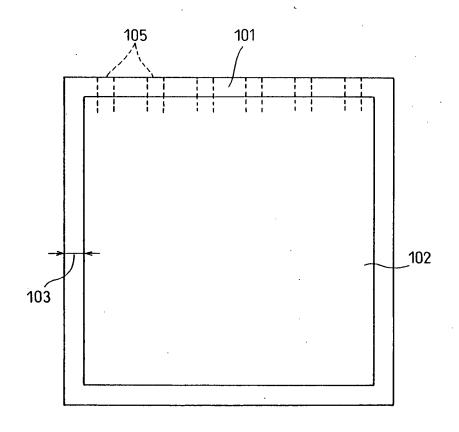


FIG.2



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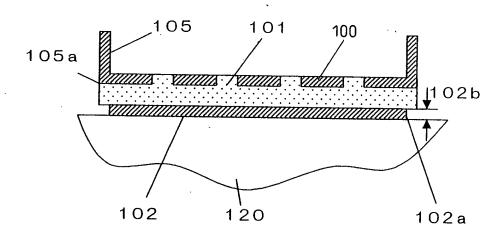
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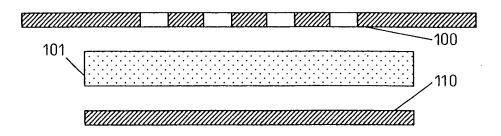


FIG.4B

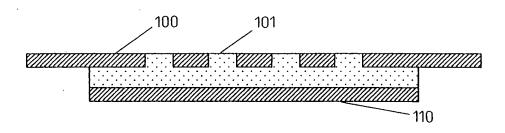
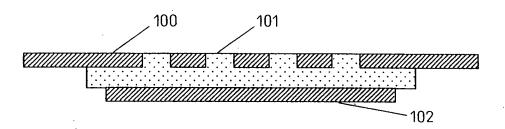


FIG. 4C



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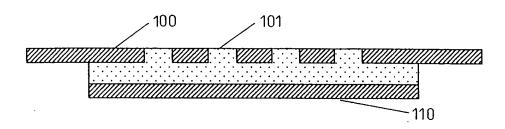
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FIG.5A



F I G. 5 B

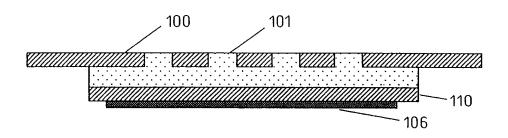
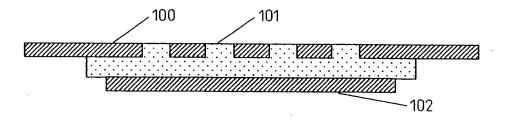


FIG.5C



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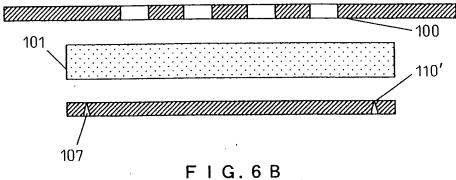
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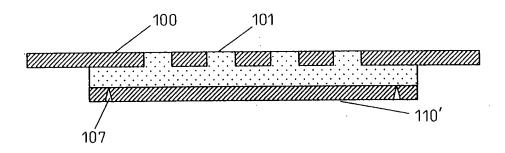
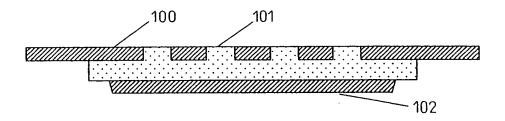
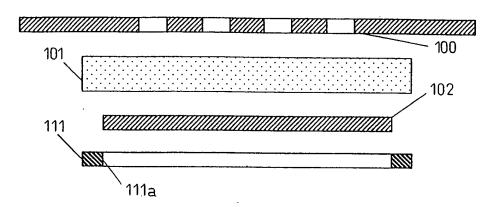


FIG.6C

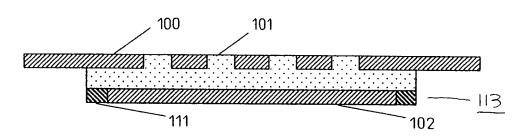


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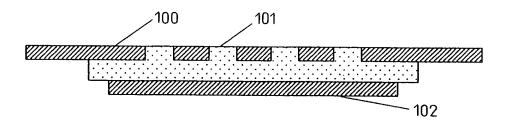
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F I G. 7 B



F I G. 7 C



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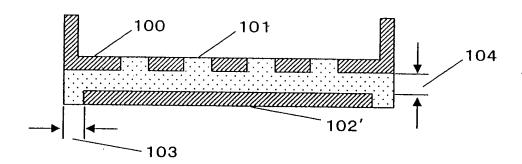
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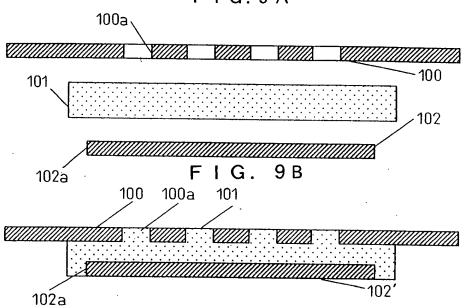
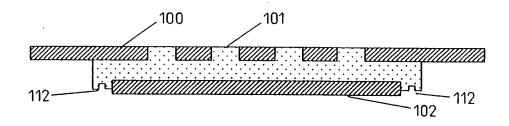
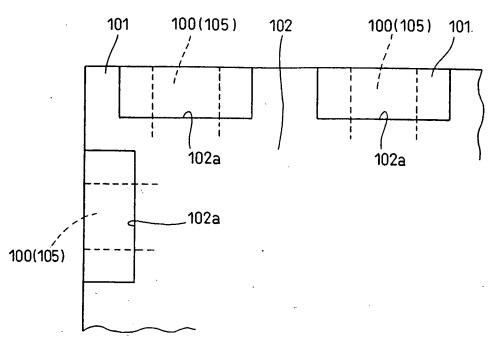


FIG. 10

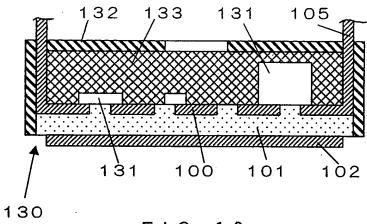


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FIG. 11



F I G. 12



F1G. 13

